APPLICATION FOR EXTENSION OF ESCC TECHNOLOGY FLOW APPROVAL

Component Title:

Thin Film Technology for Chip, Wraparound, Single and Network Resistors, Fixed

CNES

Page 1 Appl. No.

	Executive Member:	CNES		Date:	15/03/2023	287H		
Technology Flow submitted for Exten	N N-10 200 100 100	proval:				1		
SUMMARY DESCRIPTION	TE	EST STRUCTURES		C	COMPONENTS PROPOSE	ED FOR		
P: Single resistor 0402, 0603, 0805, 1206, 2010 chip PRA: 2 to 8 resistors of similar value, based on 0603 (PRA 100) 0805 (PRA135) or 1206 (PRA18 units CNW: 2 to 8 resistors with at lea two different values with the sam form factor as PRA Substrate: Alumina Resistive layer: Nickel Chromiun Protection: Silicium nitride Termination: Nickel Barrier Processes: Thin Film deposition Finish: SnPbAg or Au	with min., critic values, PRA100, PRA1 critical resistance	P0805, P1206 a cal resistance and 135, PRA182 with ce and max. valu	d max. h min.,	QUALIFICATION By form factor: ESCC4001023 var. 15 and 13, 14(*) ESCC4001023 var. 01, 05 (*) and 09 ESCC4001023 var. 02, 06 (*) and 10 ESCC4001023 var. 03, 07 (*) and 11 ESCC4001023 var. 04, 08 (*) and 12 ESCC4001025 var. 01 to 07, 22 to 28 ESCC4001025 var. 01 to 07, 22 to 28 ESCC4001025 var. 05 to 21, 36 to 42 (*) Note that gold finish variants are not intended for de-golding and tinning				
Component Manufacturer VISHAY SA		Manufacturing Plar	nt(s) 3	Date of or	iginal qualification approva	al: 4		
Division Résistances de Très Haute Précision	Nice (France)			Certificate Ref No.	. 287			
ESCC Specifications used for Maintenance testing:		Deviations to LVT testing and Detail Specification used:			Qualification Extension Report reference and date:			
Generic: 4001 Issue: 5	No □ Yes	⊠ (sup Box	ply details in 15)	QML 20	uality Synthesis repo 021 Synthesis, 06/01/2	2022		
Dotan(0). 100 1/020 10040.	Deviation from cu 8 No ⊠ Yes	urrent Specification: □ (Su	s: pply details)	QML 2022 Synthesis, 06/01/2023				
Summary of procurement or equivale	nt test results during cur	rent validity period	in support of this	application	(those to ESCC listed firs	st) 8		
Customer Compone	ent LVT	LVT Date code			Quantity Delivered	d		
TAS Belgium, RC Micro, ALTER, TTI, TAS It, RUAG PHR1206 PHR0805 PHR0603	LVT1				92 636 115 863			
TTI, ALTER, TAS It. PRA / CNV	1			2021: 2022:				
ALTER PFRR 0402	. ===				18 961 8 655			
PID changes since last maintenance	of qualification 9	Current PID Ve	erified by:		JP Busse	not, CNE\$ 10		
None		1	Fig. 1879 A recognition of a second s		Name of Excutive R	epresentative		
Minor* ⊠		Ref No:	PID-TFD P PR	RA CNW				
Major* *Provide details i	n box:	Issue:	13		Date: 27/04/20	122		
"		Date:	20/07/2022					
Current Manufacturing facilities surve	yed by: L. Fontaine	2 8		on	27/02/2023	11		
	:	Executive Represe	entative)		(Date)			
Satisfactory: Yes ⊠	No 🗆		Yes		¥ (6)			
2023.00033 Report Reference: -Vishay-Fevi	06-CR-Fontaine-Visite rier-2023	-						

ESCC Component title:

APPLICATION FOR EXTENSION OF ESCC QUALIFICATION APPROVAL

Thin Film Technology for Chip, Wraparound, Single and Network Resistors, Fixed

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nalysis, DPA, NCCS available: Yes No (Supply data) d purposes:	luro Analysis DDA NCCS a		CNES		Date: 15/03/2023	28	7H
gned hereby certifies on behalf of the ESCC Executive - that the above information is correct; - repriate documentation has been evaluated; - that full compliance to all ESCC requirements is evidence tated in box 15;) - that the reports and data are available at the ESCC Executive and therefore applies on behalf of the responsible Executive Member for ESCC qualification status to be extended to the component(s) listed herein. 15/03/2023 G.QUADRI	THE ADDITION OF A NICES OF	W. Lille					12
gned hereby certifies on behalf of the ESCC Executive - that the above information is correct; - repriate documentation has been evaluated; - that full compliance to all ESCC requirements is evidence tated in box 15;) - that the reports and data are available at the ESCC Executive and therefore applies on behalf of the responsible Executive Member for ESCC qualification status to be extended to the component(s) listed herein. G.QUADRI G.GUADRI (Signature of the Executive Coordinator)		/ailable: Yes	□ No ⊠	(Supply data)			
gned hereby certifies on behalf of the ESCC Executive - that the above information is correct; - repriate documentation has been evaluated; - that full compliance to all ESCC requirements is evidence tated in box 15;) - that the reports and data are available at the ESCC Executive and therefore applies on behalf of the responsible Executive Member for ESCC qualification status to be extended to the component(s) listed herein. 15/03/2023 G.QUADRI	No's and purposes.						
ropriate documentation has been evaluated; - that full compliance to all ESCC requirements is evidence tated in box 15;) - that the reports and data are available at the ESCC Executive and therefore applies on behalf of the responsible Executive Member for ESCC qualification status to be extended to the component(s) listed herein. 15/03/2023 G.QUADRI G.Q	undersigned hereby andiffer on helps	of the ESCC Expension	that the above in	oformation is correct.			13
15/03/2023 G.QUADRI (Signature of the Executive Coordinator) of Boxes above:	the appropriate documentation has b	een evaluated: - that full of	compliance to all E	SCC requirements is	evidence	6	7 10
(Signature of the Executive Coordinator) of Boxes above:	ept as stated in box 15;) - that the rep ES as the responsible Executive Mer	mber for ESCC qualificati	on status to be ext	ended to the compone	ent(s) listed herein.	1000	ne
(Signature of the Executive Coordinator) of Boxes above:	45/02/2022					COLLADDI SAA	1
of Boxes above:	9: 15/03/2023						r)
		paragraph 6 of the Tech	nology Flow PID	(See page 3)			14
	to it criticals recally to actifica in p	anagraph o or the room	lology i low i ib i	occ page o,			



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CNES

Executive Member:

Date: 15/03/2023

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Non comp	bliance to ESCC requirements:		
No.:	Specification	Paragraph	Non compliance
1	4001	Chart F4	Chart F4 testing replaced with the implementation of periodic testing as described in PID paragraph 6.3
Additional noncompl	tasks required to achieve full compliance for iance:	ESCC qualification or rationale for acceptability	of16
None			
Executive	Manager Disposition		17
Application Action / Re	n Approval: Yes ⊠ No □ emarks:		
Date:			B. 201
			B. Schade: Head of the Product Assurance and Safety Department



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15/03/2023 CNES Date:

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ANNEX 1: LIST OF TESTS DONE TO SUPPORT EXTENSION OF QUALIFICATION

Executive Member:

Tests conducted in compliance with:

ESCC 4001 generic specification; Chart F4 (for ESCC/QPL parts); or PID-TFD **P PRA CNW Issue 12** (for ESCC/QML parts)

Tests vehicle identification/description:

PHR2010 dc 2037 (160K)	PRAHR dc 2014 (22K)	
PHR0805 dc 2028 (160K)	CNWHR dc 2007 (2K49/10K)	
PHR0805 2109 (1K21)	PHR0402 dc 2118 (1K)	
PHR1206 dc 2109 (15K)	PHR0402 dc 2119 (11K)	
PHR2010 2109 (79K6)	PHR2010 dc 2120 (182K)	
PHR0402 dc 2128 (30R)	PHR0603 dc 2150 (470R)	
PHR0603 dc 2136 (3K16)	PHR0805 dc 2204 (1K)	
PHR1206 dc 2140 (243R)	PHR2010 dc 2143 (1M2)	
PRAHR dc 2103 (16K2)	PRAHR dc 2224 (20K4)	
PRAHR dc 2103 (10K)	PRAHR dc 2214 (33K2)	
PRAHR dc 2110 (4K7)	FRAIII do 2214 (33N2)	

4001/023 & 4001/025 Detail Specification reference:

Extracted from 2021 & 2022 QML Synthesis

Chart F4	Test	Tick when done	Conditions	Date Code	Teste d Qty	N° of Rejects	Comments if not performed. Comments on Rejection
nical Subgroup (1)	Mounting	⊠	IEC 60115-1 clause 4.31	2028 2037 2014 2007 2109 2109 2118 2119 2120 2128 2136 2140 2103 2103 2110 2150 2204 2143 2224 2214	555555555555555555555	0	
Environmental /Mechanical Subgroup (1)	Rapid Change Of Temperature	×	IEC 60068-2-14	2028 2037 2014 2007 2109 2109 2118 2119 2120 2128 2136 2140 2103 2110 2150 2204 2143 2224 2214	555555555555555555555555	0	
	Vibration		IEC 60068-2-6				NA

Climatic test Sequence Secc 4001, Para Secc 4001, Para Sequence Secc 4001, Para Sequence Secc 4001, Para Secc 4001, Par								
Seal Test		Climatic test Sequence	⊠	ESCC 4001, Para 8.10	2037 2109 2109 2109 2118 2119 2120 2128 2136 2140 2150 2204	5 5 5 5 5 5 5 5 5 5 5 5	0	
Mounting Mounting		Seal Test		IEC 60068-2-17				NA
Robustness of Terminations IEC 60068-2-21 2028 2 2 2 2 2 2 2 2 2		Mounting	⊠		2037 2109 2109 2109 2118 2119 2120 2128 2136 2140 2150 2204	2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	0	
Climatic test Sequence ESCC 4001, Para 8.10 ESCC 4001, Para 2119 2 2120 2 2128 2 2136 2 2140 2 2150 2 2150 2 2204 2 2143 2	onmental /Mechanical Subgroup (2)		⊠	IEC 60068-2-21	2037 2109 2109 2109 2118 2119 2120 2128 2136 2140 2150 2204	2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	0	Adhesion followed with Substrate bending
	Enviro	Climatic test Sequence	⊠	ESCC 4001, Para 8.10	2028 2037 2109 2109 2109 2118 2119 2120 2128 2136 2140 2150 2204	2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	0	
		Seal Test		IEC 60068-2-17				NA

Environmental /Mechanical Subgroup (3)	Resistance to Soldering Heat	⊠	IEC 60068-2-20	2028 2037 2014 2007 2109 2109 2119 2118 2119 2120 2128 2136 2140 2103 2103 2110 2150 2204 2143 2224 2214	2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	0	
al ∖	Mounting		IEC 60115-1 clause 4.31				
Environmen	Climatic test Sequence	⊠	ESCC 4001, Para 8.10	2028 2037 2109 2109 2118 2119 2120 2128 2136 2140 2150 2204 2143	2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	0	
	Seal Test		IEC 60068-2-17			- 10	NA
	Mounting	- 🗆	IEC 60115-1 clause 4.31				
Environmental /Mechanical Subgroup (4)	Insulation Resistance	⊠	ESCC 4001, Para 8.3.1.2	2028 2037 2109 2109 2118 2119 2120 2128 2136 2140 2150 2204 2143 2224 2214	5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5	0	
Environmental ,	Voltage Proof	⊠	ESCC 4001, Para 8.3.1.3	2028 2037 2109 2109 2118 2119 2120 2128 2136 2140 2150 2204 2143	555555555555555	0	
Endurance Subgroup	Mounting		IEC 60115-1 clause 4.31	2014 2007 2128 2103 2103 2110 2224	10 (*) 10 (*) 15 10 (*) 10 (*) 10 (*) 10 (*)	0	(*) performed after Solderability / Permanence of Marking Sequence
iduranci			ESCC 4001, Para	2214	10 (*)		PRAHR135

				2128 2103 2103 2110 2224 2214	15 10 (*) 10 (*) 10 (*) 10 (*) 10 (*)		PHR Low Ohmic value PRAHR100 PRAHR135 PRAHR182 PRAHR PRAHR
	Seal Test		IEC 60068-2-17				NA
Assembly Capability Subgroup	Solderability		IEC 60068-2-20	2028 2037 2014 2007 2109 2109 2118 2119 2120 2128 2136 2140 1917 1921 1907 2005 2007 2009 2103 2110 2150 2204 2143 2224 2214	2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 5 5 5 2 2 2 2 5 5	0	
	Permanence of marking	⊠	ESCC 24800	2014 2007 2103 2103 2110 2224 2214	5 5 5 5 5 5 5 5 5 5	0	PRA / CNW
Failure Rate Endurance Subgroup	Operating Life	×	ESCC 4001, Para 8.13	Febr. '20 to May '21 - June '21 to Sept. '22	180 450 210 240 - 0 510 0 450	0	2 000H 4 000H 6 000H 8 000H - 2000H 4000H 6000H 8000H
	Seal Test		IEC 60068-2-17				NA
Additional Tests	High & Low Temp (Temperature Coefficient)		ESCC 4001	2028 2037 2014 2007 2109 2109 2118 2119 2120 2128 2136 2140 2103 2103 2110 2150 2204 2143 2224 2214	555555555555555555555555	0	(*) performed before Rapid Change of Temperature



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Date: 15/03/2023 Executive Member: CNES

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NOTES ON THE COMPLETION OF THE APPLICATION FORM FOR ESCC QUALIFICATION EXTENSION APPROVAL

ENTRIES	
Form heading	shall indicate: - the title of the component as given in its detail specification or the name of the series, family; - the Executive Member; - the entering date; - the certificate number and its sequential suffix.
Box 1	shall provide details given in the table; in particular there shall be listed: - the variants or range of variants; - the range of components (the ESCC code is recommended to indicate the values or values range, the tolerance, the voltage, etc); the designation given in the detail specification as 'base on'; - under Test Vehicle enter either an ESCC code or the specific characteristic capable of identifying the component tested (e.g., voltage of coil for a relay); - under component similar enter a cross if relevant.
Box 2; 3 and 4	As per QPL entry; otherwise, an explanation of the changes must be supplied.
Box 5	Will show the ESCC Generic and Detail specifications, including issue number and revision letter, current at the time the tests reported were performed. If the specifications are different from those current on the date of the application, see Box 6.
Box 6	Will show the deviations from the Generic and Detail Specifications listed in Box 5, in particular deviations from testing. In case of deviations this must be listed in Box 15. In case the referenced specification in Box 5 have currently a different issue and/or revision indicate also whether the test data deviates or not from such current documents.
Box 7	Must reference the report(s) supplied in support of the application.
Box 8	Should provide the details of procurement to the full ESCC System, documentation of all of which should already have been delivered to the ESCC Executive under the terms of the relevant Generic Specification. An appropriate table has been drawn in this box.
Box 9	If the PID evolved after the Original Qualification or after the last Extension of Qualification, adequate details of such evolution shall be provided together with the reasons for the changes. Major changes shall be clearly marked.
Box 10	Identify the current PID issue status, date and actual date of verification. The date of verification of the current PID should be arranged as close as possible to the required date of extension.
Box 11	This box can be completed only after a physical visit to the plant to confirm that no unexplained changes occurred and that the practices, procedures, material, etc. used in manufacturing the components are as described in the PID. This survey shall be carried out in accordance with the requirements of ESCC Basic Specification No. 20200 and its findings shall be recorded.
Box 12	Provide details of, or reference to, any Destructive Physical Analysis (DPA) and Failure Analysis reports as well as any Nonconformance(s) (NCCS) occurred during the qualification validity period, stating if established corrective action have produced satisfactory results.
Box 13	Enter only the name of the Executive Member (i.e., CNES, DLR, ESTEC, etc.) and the signature of the responsible Executive Coordinator.
Box 14	To be used when there is a need to expand any of the boxes from 1 through 12. Identify box affected and reference the Box 14 in the relevant Box. Box 14 can be broken into 14a, 14b, etc. if several boxes have to be expanded.
Box 15	Fill in Table as requested.
Box 16	Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance.
Box 17	All Executive Manager recommendations on the application itself, special conditions or restrictions, modifications of the QPL or QML entry, letters to the manufacturer, etc. shall be entered clearly in Box 19, signed by the representative for ESA, and dated.
Box 18	Fill in Table as requested.
Box 19	Confidential Details of PID changes including those of a confidential nature, shall be provided.
Box 20	State noncompliance with reference to specification(s) and paragraph(s). To simplify reference in Box 16 each nonconformance shall be sequentially numbered. If relevant state 'None'.
Box 21	Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance.
Box 22	Additional Comments.